

MOSFET - N-Channel, QFET

200 V, 19 A, 170 mΩ

FQP19N20C, FQPF19N20C

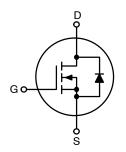
Description

This N-Channel enhancement mode power MOSFET is produced using **onsemi**'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

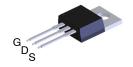
Features

- 19 A, 200 V, $R_{DS(on)} = 170 \text{ m}\Omega$ (Max) @ $V_{GS} = 10 \text{ V}$, $I_D = 9.5 \text{ A}$
- Low Gate Charge (Typ. 40.5 nC)
- Low C_{rss} (Typ. 85 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

V _{DS}	R _{DS(ON)} MAX	I _D MAX	
200 V	170 mΩ @ 10 V	19 A	



N-Channel MOSFET



TO-220-3LD CASE 340AT



TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT

MARKING DIAGRAM



FQP19N20C

1

FQPF19N20C = Device Code
A = Assembly Location
YWW = Date Code (Year & Week)

ZZ = Assembly Lot

ORDERING INFORMATION

Device	Package	Shipping
FQP19N20C	TO-220	1000 Units / Tube
FQPF19N20C	TO-200F	1000 Units / Tube

MOSFET MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter		FQP19N20C FQPF19N20C		Unit
V _{DSS}	Drain to Source Voltag	е	200		V
I _D	Drain Current	– Continuous (T _C = 25°C)	19.0	19.0*	Α
		– Continuous (T _C = 100°C)	12.1	12.1*	
I _{DM}	Drain Current	- Pulsed (Note 1)	76.0	76.0*	Α
V_{GSS}	Gate to Source Voltage	e	±30		V
E _{AS}	Single Pulsed Avalanc	he Energy (Note 2)	433		mJ
I _{AR}	Avalanche Current (No	ote 1)	19.0		Α
E _{AR}	Repetitive Avalanche E	Energy (Note 1)	13.9		mJ
dv/dt	Peak Diode Recovery	dv/dt (Note 3)	5.5		V/ns
P_{D}	Power Dissipation	(T _C = 25°C)	139	43	W
		-Derate above 25°C	1.11	0.34	W/°C
T _J , T _{STG}	Operating and Storage	e Temperature Range	-55 to +150		°C
T _L	Maximum Lead Tempe 1/8" from Case for 5 Se		300		°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
*Drain current limited by maximum junction temperature.

THERMAL CHARACTERISTICS

Symbol	Parameter	FCP190N60	FCPF190N60	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.9	2.89	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	62.5	

^{1.} Repetitive rating: pulse–width limited by maximum junction temperature. 2. L = 1.8 mH, I_{AS} = 19.0 V, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. $I_{SD} \le$ 19.0 A, di/dt \le 300 A/ μ s, $V_{DD} \le$ BV_{DSS}, starting T_{J} = 25°C.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
FF CHARA	ACTERISTICS		•	•		
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	200	-	_	V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	-	0.24	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 200 V, V _{GS} = 0 V	-	-	10	μΑ
		V _{DS} = 160 V, T _C = 125°C	-	-	100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	-	-	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	-	-	-100	nA
N CHARA	CTERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.0	-	4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 9.5 A	-	0.14	0.17	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 9.5 A	-	10.8	_	S
YNAMIC C	HARACTERISTICS					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	-	830	1080	pF
C _{oss}	Output Capacitance	1	-	195	255	pF
C _{rss}	Reverse Transfer Capacitance	1	_	85	110	pF
WITCHING	CHARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 100 V, I _D = 19.0 A,	_	15	40	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$ (Note 4)	_	150	310	ns
t _{d(off)}	Turn-Off Delay Time		-	135	280	ns
t _f	Turn-Off Fall Time	1	-	115	240	ns
Qg	Total Gate Charge	V _{DS} = 160 V, I _D = 19.0 A _,	-	40.5	53.0	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V (Note 4)	_	6.0	-	nC
Q_{gd}	Gate-Drain Charge	,	_	22.5	_	nC
RAIN-SOU	RCE DIODE CHARACTERISTICS AND N	IAXIMUM RATINGS				
IS	Maximum Continuous Drain-Source Diode Forward Current		_	-	19.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	76.0	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 19.0 A	-	-	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 19.0 A,	-	208	-	ns
Q _{rr}	Reverse Recovery Charge	dl _F /dt = 100 A/μs	-	1.63	_	μС

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially Independent of Operating Temperature.

TYPICAL CHARACTERISTICS

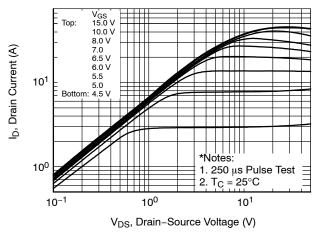


Figure 1. On-Region Characteristics

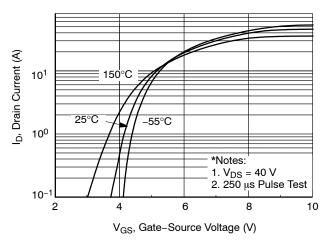


Figure 2. Transfer Characteristics

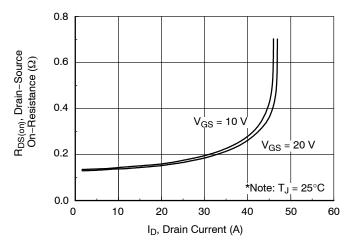


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

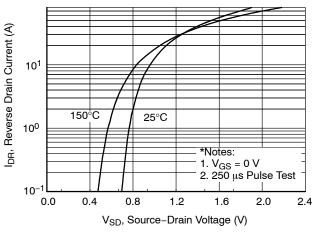


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

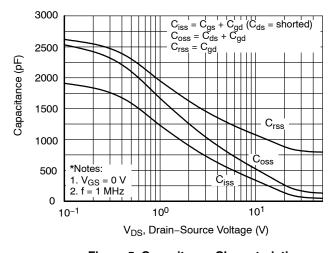


Figure 5. Capacitance Characteristics

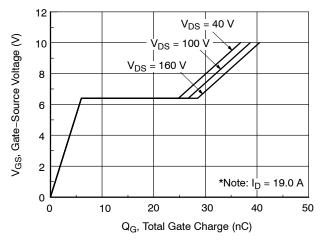


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS (continued)

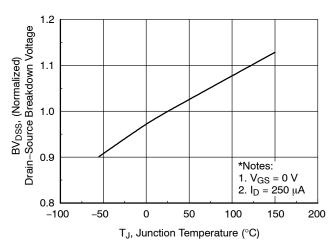


Figure 7. Breakdown Voltage Variation vs Temperature

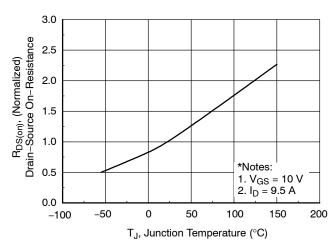


Figure 8. On-Resistance Variation vs Temperature

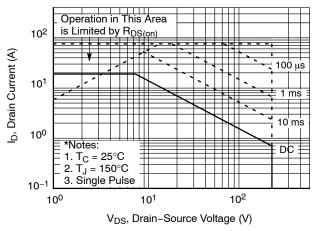


Figure 9.1. Maximum Safe Operating Area for FQP19N20C

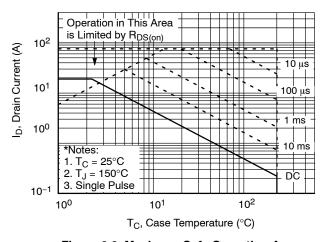


Figure 9.2. Maximum Safe Operating Area for FQPF19N20C

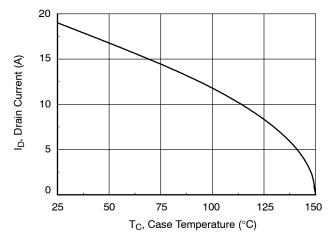


Figure 10. Maximum Drain Current vs Case Temperature

TYPICAL CHARACTERISTICS (continued)

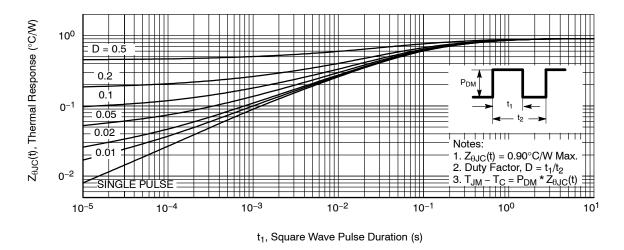


Figure 11.1. Transient Thermal Response Curve for FQP19N20C

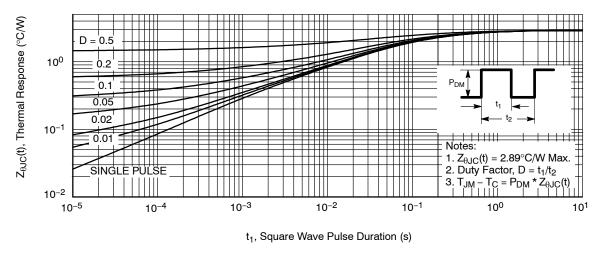


Figure 11.2. Transient Thermal Response Curve for FQPF19N20C

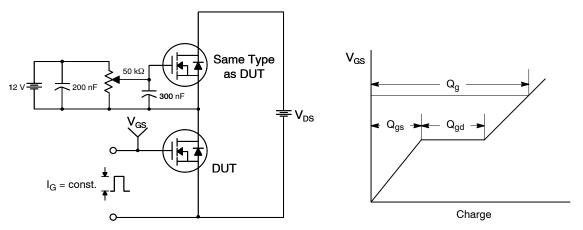


Figure 12. Gate Charge Test Circuit & Waveform

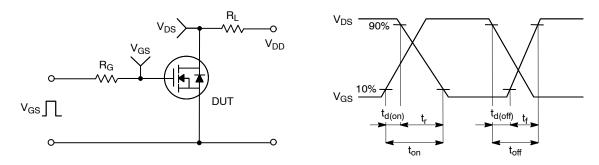


Figure 13. Resistive Switching Test Circuit & Waveforms

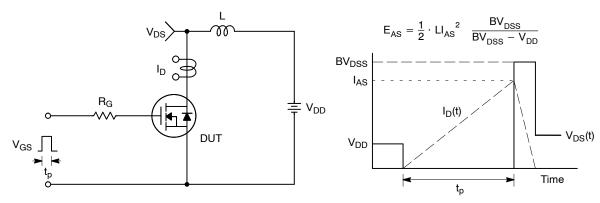


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

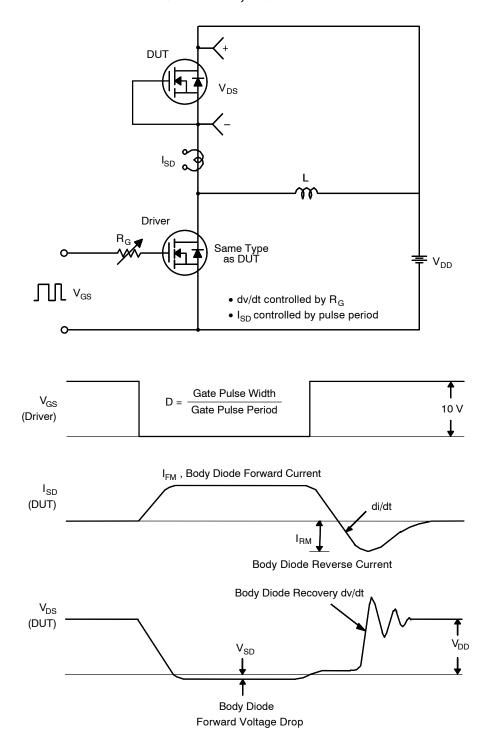
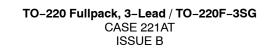
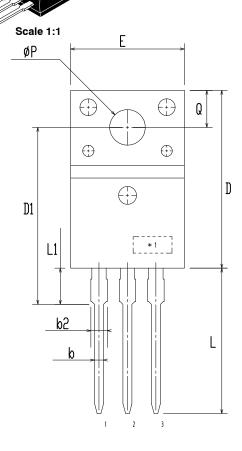
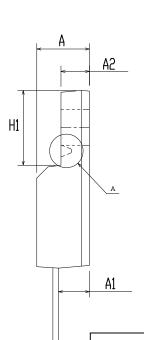


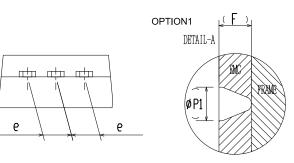
Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



DATE 19 JAN 2021







DIM	MIL	LIMITERS	
DIM	MIN	NDM	MAX
Α	4.50	4.70	4.90
A1	2.56	2.76	2.96
A2	2.34	2.54	2.74
b	0.70	0.80	0.90
b2	*	2	1.47
C	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.60	15.80	16.00
E	9.96	10.16	10.36
е	2.34	2.54	2.74
F	~	0.84	~
H1	6.48	6.68	6.88
Ш	12.78	12.98	13.18
L1	3.03	3.23	3.43
ØΡ	2.98	3.18	3.38
Ø P1	~	1.00	~
Q	3.20	3.30	3.40

NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.

C

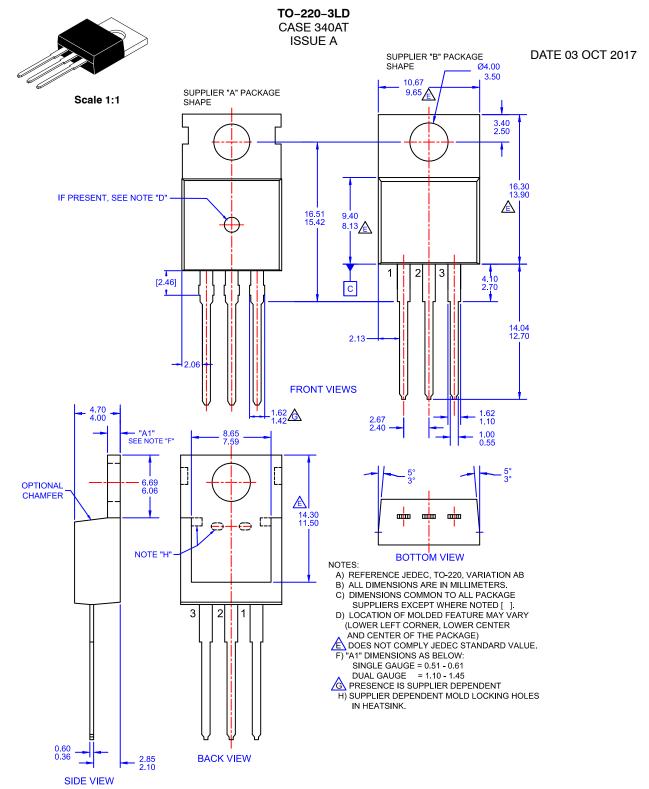
C. OPTION 1 - WITH SUPPORT PIN HOLE

OPTION 2 - NO SUPPORT PIN HOLE

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